

TEXAS INSTRUMENTS

BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	SOLDERPASTE - PRIMARY SIDE
PROJECT #:	DLP-30179-02	DATE:	12 NOV 2018
		REVISION:	

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	12.0	+3.0/-12.0	PLATED	1107
A	63.0	+3.0/-3.0	PLATED	11
△	60.2	+2.0/-2.0	NON-PLATED	9
+	78.7	+2.0/-2.0	NON-PLATED	1
○	146.0	+3.0/-3.0	NON-PLATED	4
+	189.0	+3.0/-3.0	NON-PLATED	4

FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010". DIMENSIONS ARE FOR REFERENCE ONLY. USE ARTWORK FOR ACCURATE MEASUREMENT OF THE BOARD OUTLINE.
- THE PWB SHALL BE FABRICATED TO IPC-6011 AND IPC-6012, CLASS 2, TYPE 3. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT. RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
- BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD. ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94-0 REGISTERED MATERIAL ID NUMBER.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
- OVERALL BOARD THICKNESS TO BE .062 +/- .010" AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- INNER PLANE LAYERS TO BE 1/2 OZ. COPPER. INNER SIGNAL LAYERS TO BE 1/2 OZ. COPPER. OUTER LAYERS TO BE 1/2 OZ. COPPER + PLATING.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- ALL HOLES ARE ON A 0.0001 GRID EXCEPT THOSE INDICATED.
- MAXIMUM RATED VOLTAGE BETWEEN CONDUCTORS SHALL BE 65 VOLTS PEAK.
- NO BREAKOUT ALLOWED ON PLATED THROUGH HOLES.
- FOIL OUTER OPTIONAL.
- INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994.
- TEARDROP VIAS AS NECESSARY.
- THIEVING IS NOT ALLOWED.

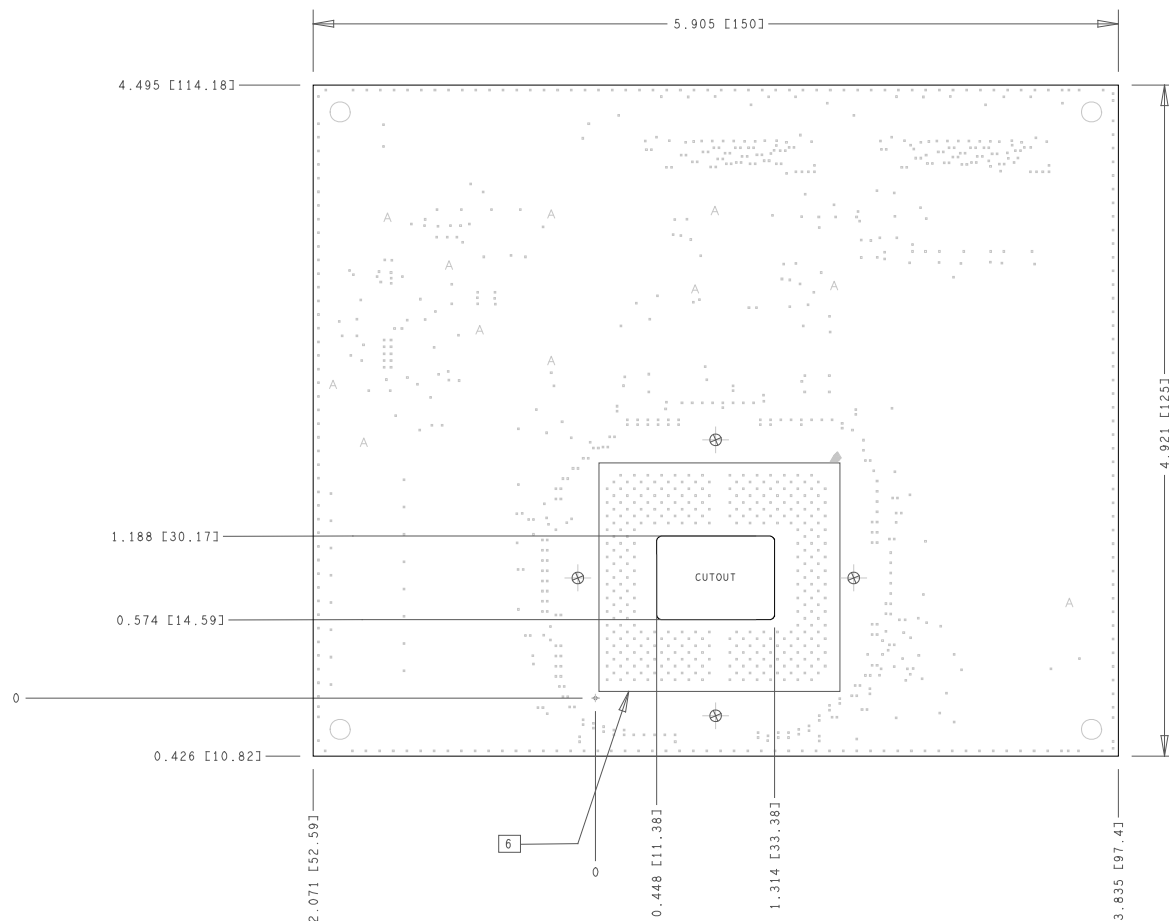
PROCESS NOTES:

- EXCEPT AS NOTED BELOW, ALL EXPOSED CONDUCTORS ON BOTH SIDES PWB SHALL BE ELECTROPLATED GOLD (5-15 MICROINCHES) OVER ELECTROPLATED NICKEL (50 MIN MICROINCHES).

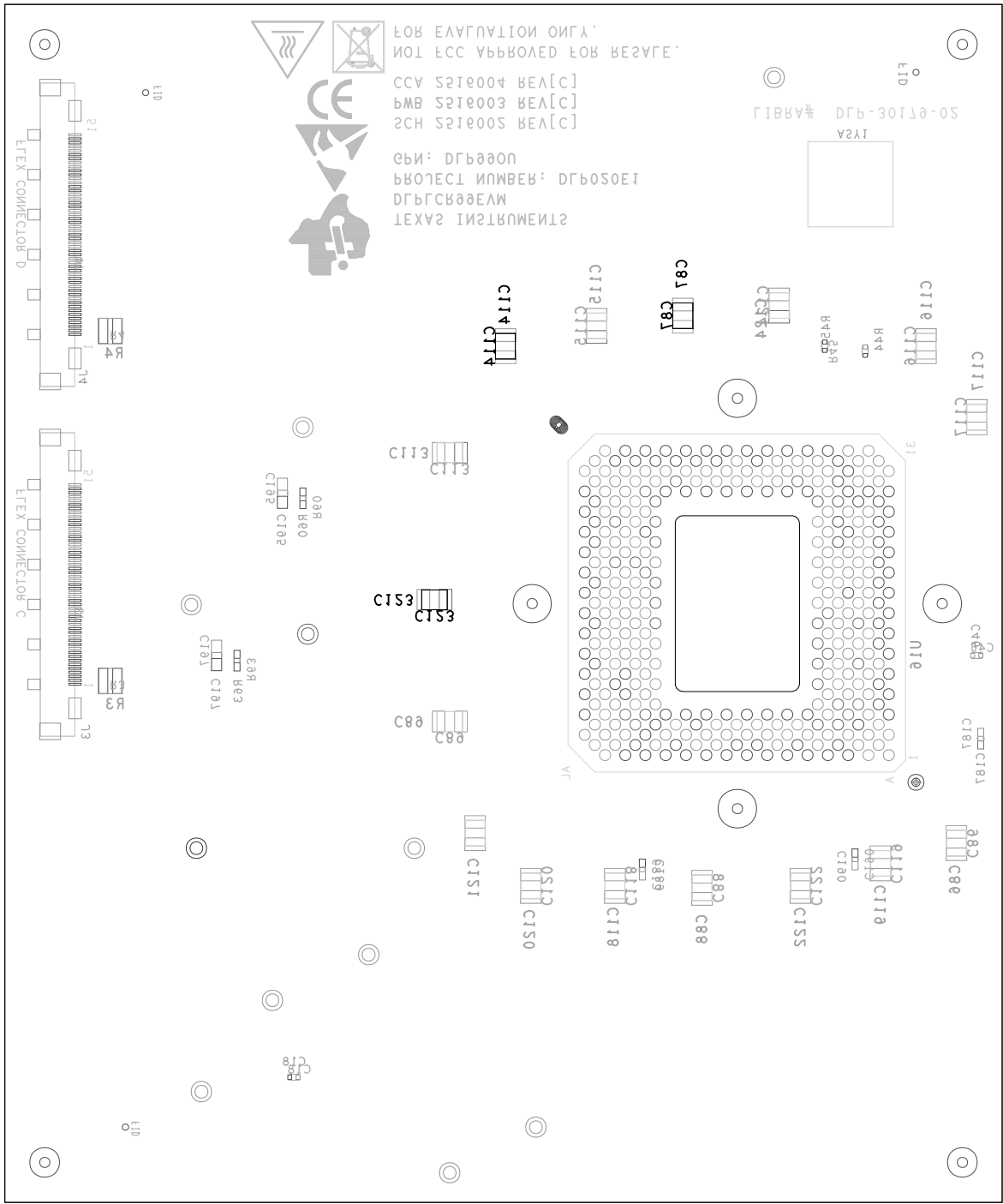
- APPLY LPI SOLDERMASK. COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H, CURRENT REV.
- FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- APPLY LPI SILKSCREEN OR EQUIVALENT BOTH SIDES PER THE ARTWORK. COLOR: WHITE.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- PLATE INDICATED PAD AREAS WITH A MINIMUM OF 30. MAXIMUM OF 50 MICROINCHES ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 50 MICROINCHES OF ELECTROLYTIC NICKEL.

CONTROLLED IMPEDANCE

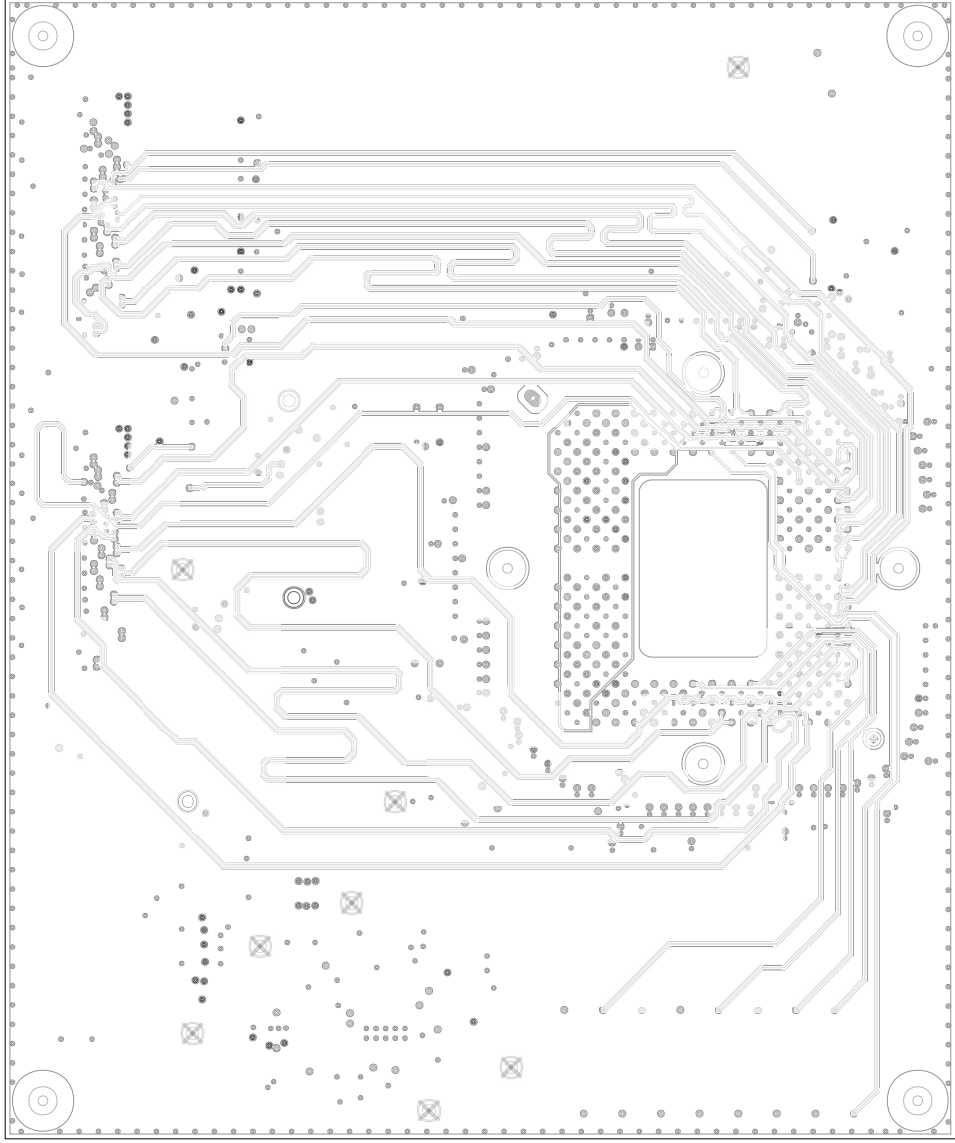
LAYER STACKUP	50 OHMS SINGLE ENDED +/-10%	WIDTH/SPACING 100 OHMS DIFFERENTIAL +/-10%
LAYER 1 - PRIMARY SIDE/GND FILL		
LAYER 2 - SIGNAL	0.0057"	0.0048/0.0074
LAYER 3 - GND PLANE		
LAYER 4 - SIGNAL	0.0065	0.0050/0.0072
LAYER 5 - GND PLANE		
LAYER 6 - SIGNAL	0.0047"	0.0042/0.0080
LAYER 7 - GND PLANE		
LAYER 8 - SECONDARY SIDE/PWR FILL		



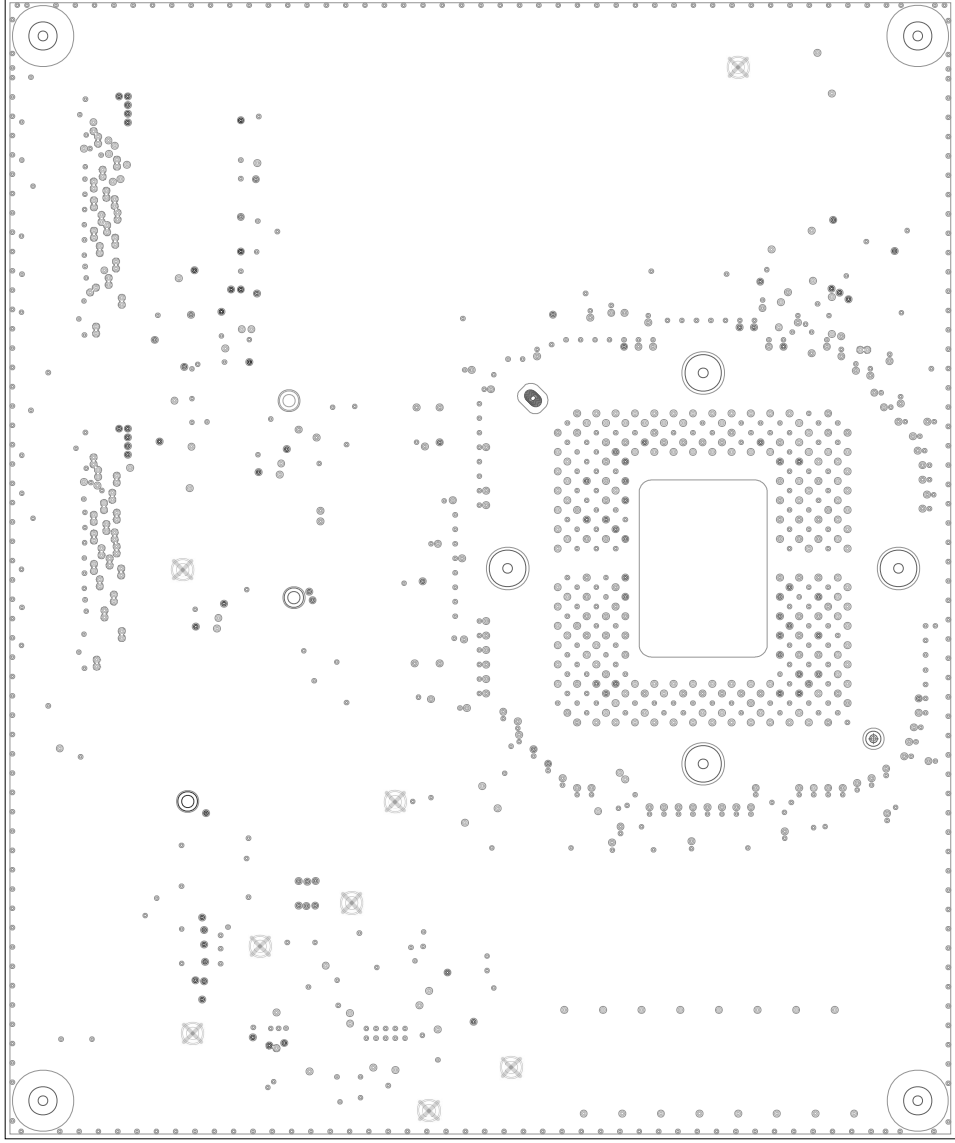
TEXAS INSTRUMENTS			
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	FAB DRAWING
PROJECT #:	DLP-30179-02	DATE:	12 NOV 2018
		REVISION:	



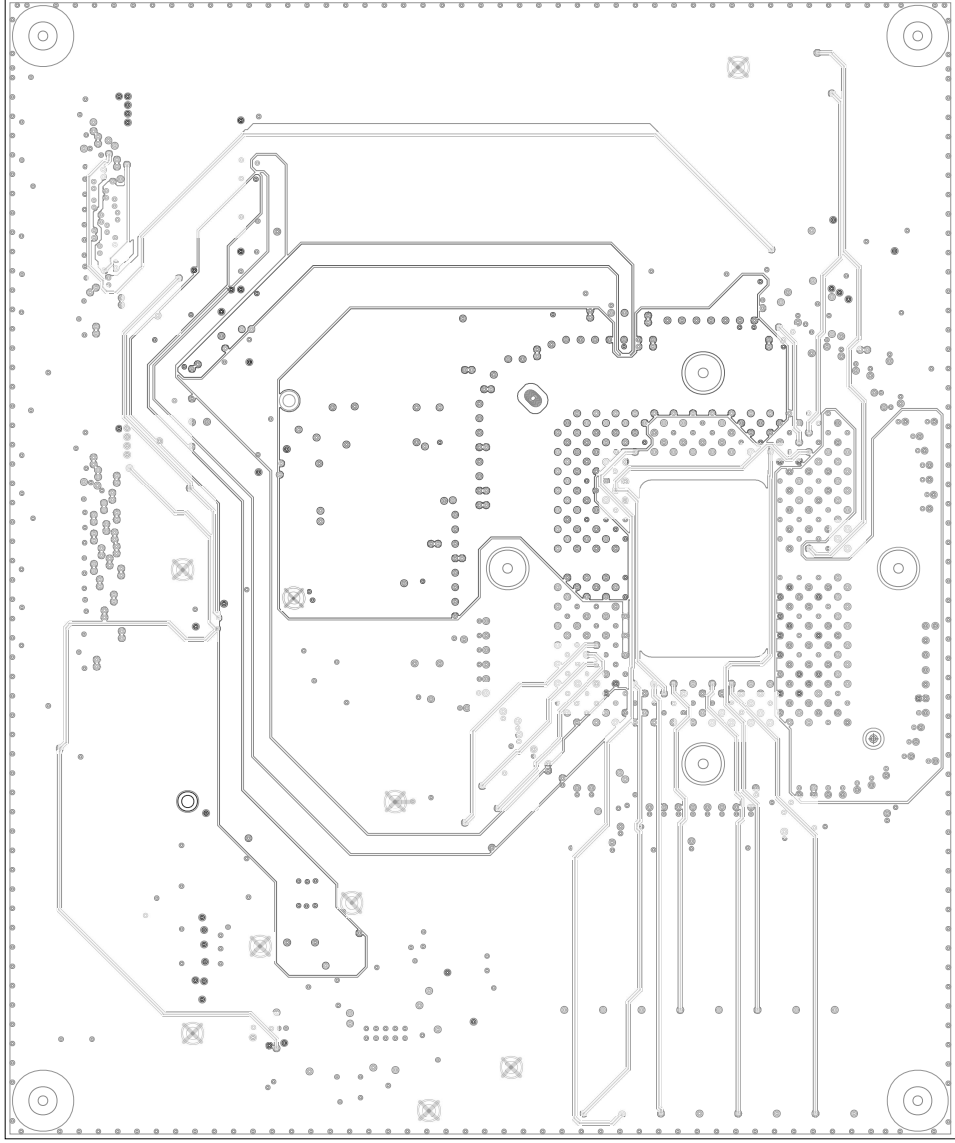
TEXAS INSTRUMENTS ASSEMBLY - SECONDARY SIDE	
BOARD NAME: 0.98 HSSI DMD BOARD	DESCRIPTION: SILKSCREEN - SECONDARY SIDE
PROJECT #: DLP-30179-02	DATE: 12 NOV 2018
REVISION:	



TEXAS INSTRUMENTS			
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	LAYER 4 - SIGNAL
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TEXAS INSTRUMENTS			
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	LAYER 3 - GND PLANE
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TEXAS INSTRUMENTS		
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION: LAYER 2 - SIGNAL
PROJECT #:	DLP-30179-02	DATE: 12 NOV 2018
		REVISION:

ART FILM - asb



FLEX CONNECTOR D



L1D

FLEX CONNECTOR C



L1D



FOR EVALUATION ONLY:
NOT FCC APPROVED FOR RESALE.
CCA S210004 REV[C]
BMB S210003 REV[C]
SCH S210005 REV[C]
BYN: DGB000P
PROJECT NUMBER: DGB0500E1
DGBGC000EAM
TEXAS INSTRUMENTS

= R60
= C102

C111

= R63
= C103

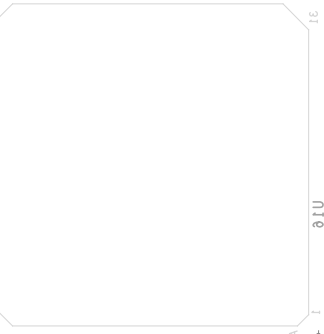
C113

C153

C66

C151

C150



C114

C112

C61

C180

C68

C118

C155

= C100

C110

C154

R42

R44

C110

C111

C4011 = C181

C60

L1BKA# DGB-30179-05



L1D



TEXAS INSTRUMENTS

BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	SILKSCREEN - SECONDARY SIDE
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ART FILM - asb

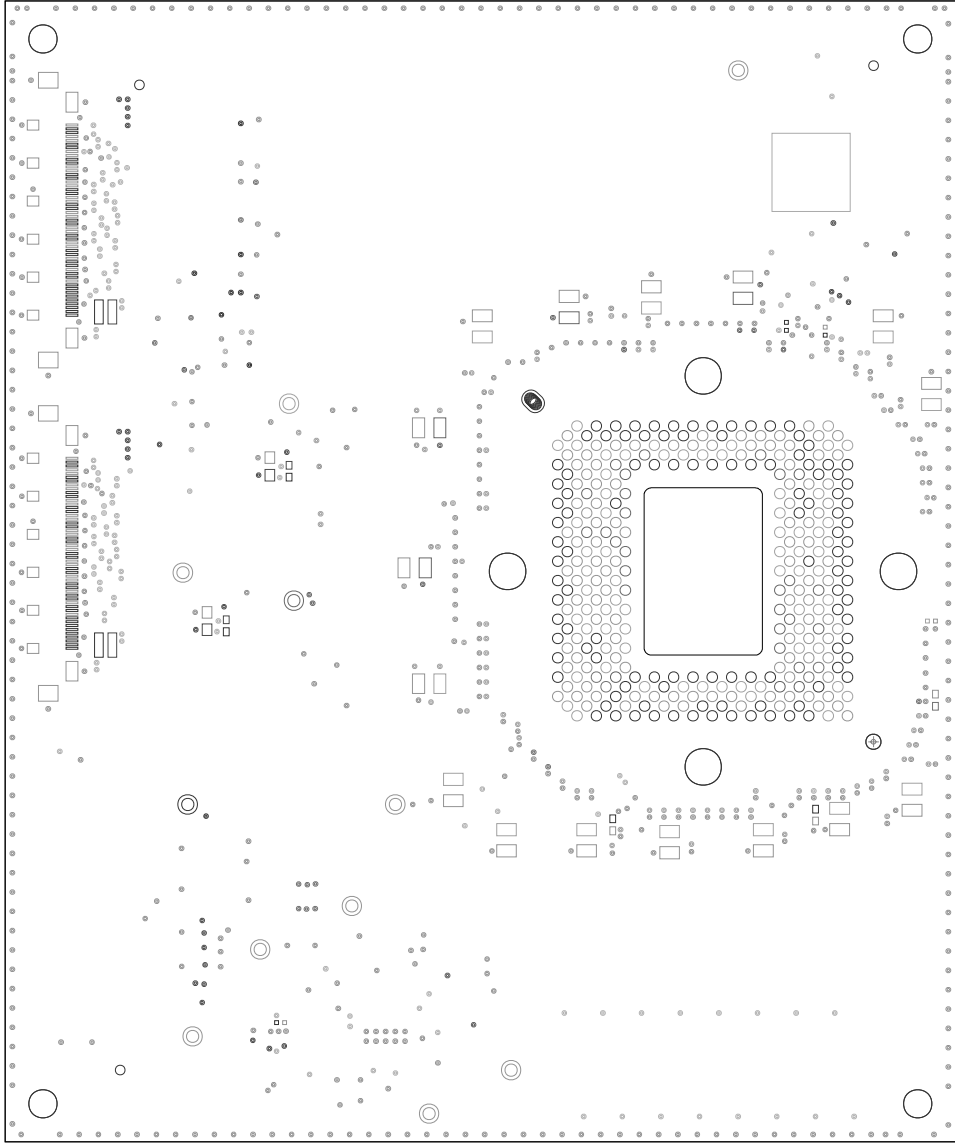




TEXAS INSTRUMENTS

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DESCRIPTION: SILKSCREEN - PRIMARY SIDE	
PROJECT #:	DLP - 30179 - 02
DATE:	12 NOV 2018
REVISION:	

ART FILM - smb

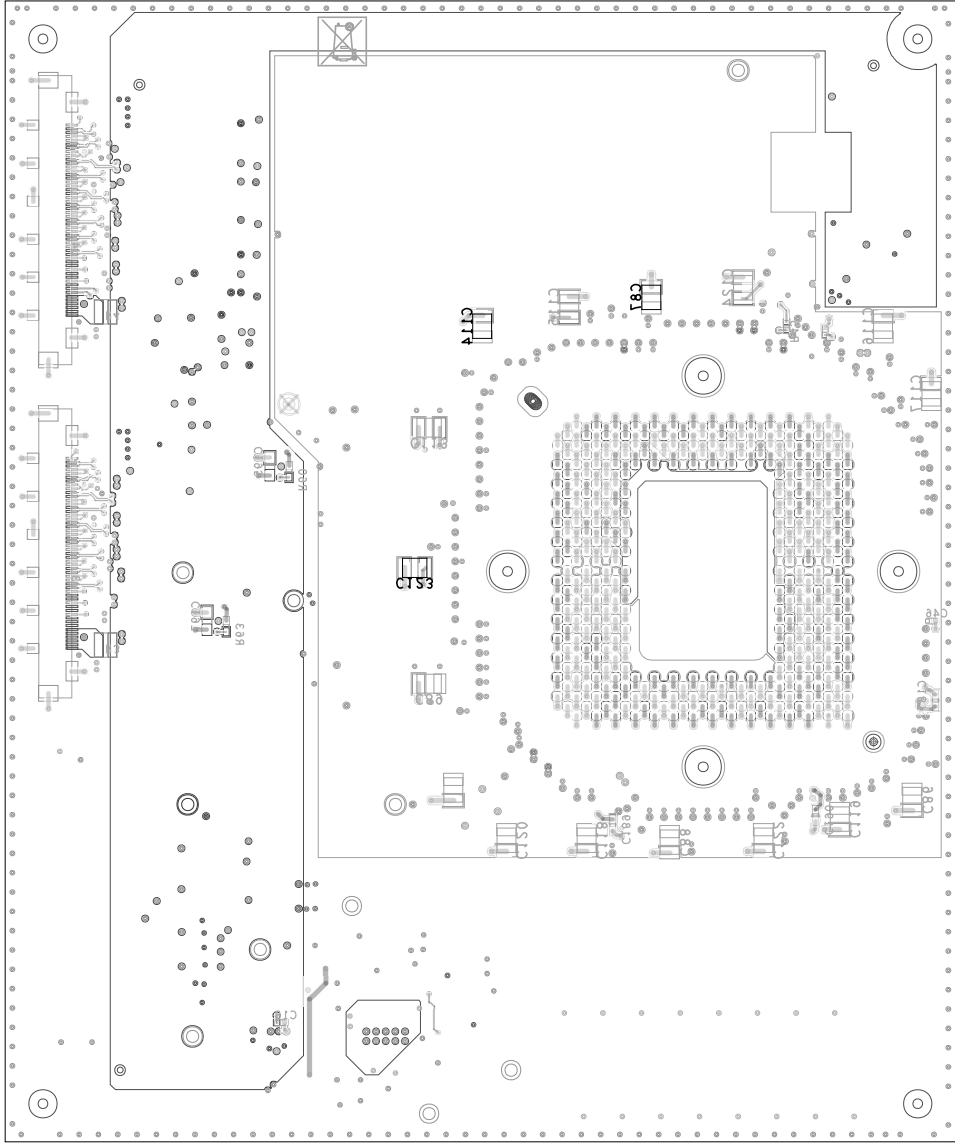


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BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION: SOLDERMASK - SECONDARY SIDE	
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ART FILM - smb



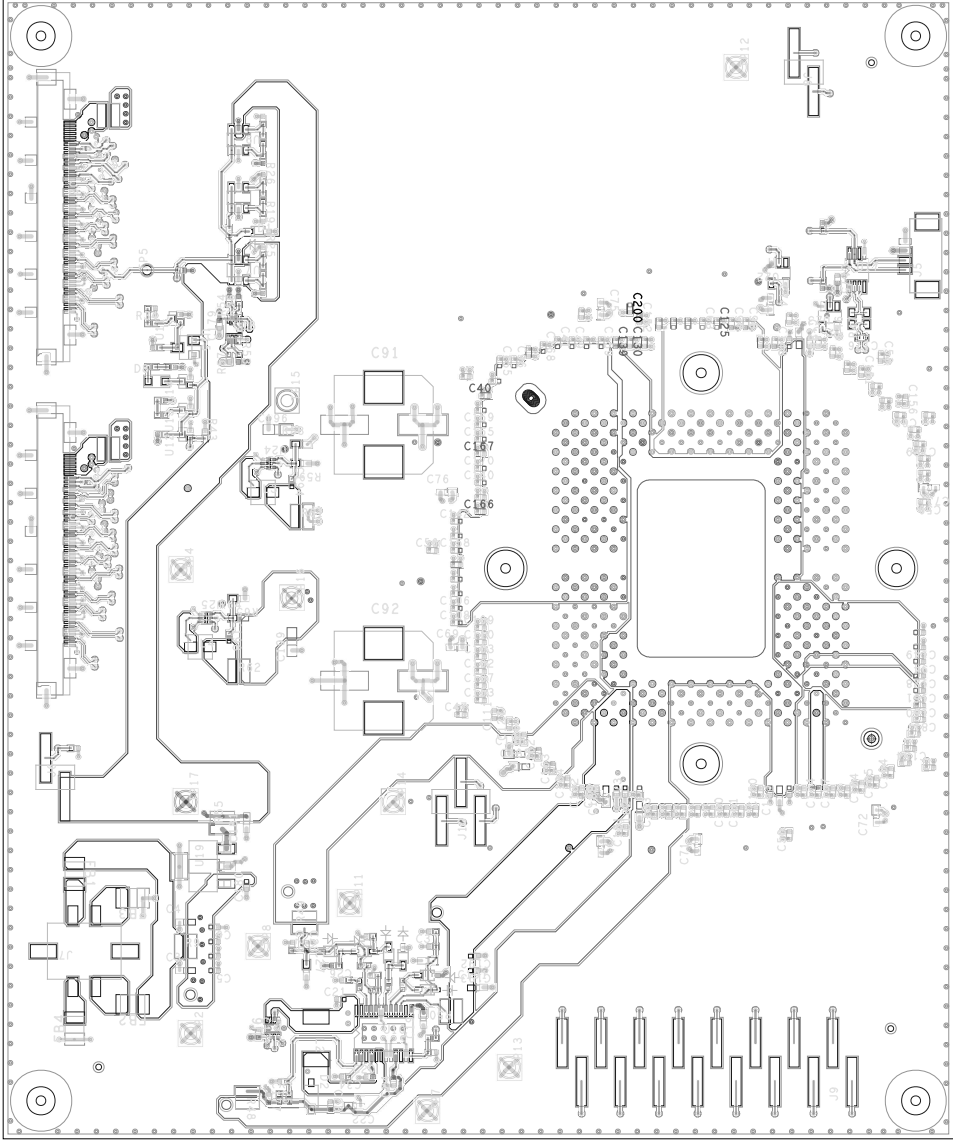
ART FILM - bottom



TEXAS INSTRUMENTS		ASSEMBLY - SECONDARY SIDE	
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	LAYER 8 - SECONDARY SIDE
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ART FILM - bottom

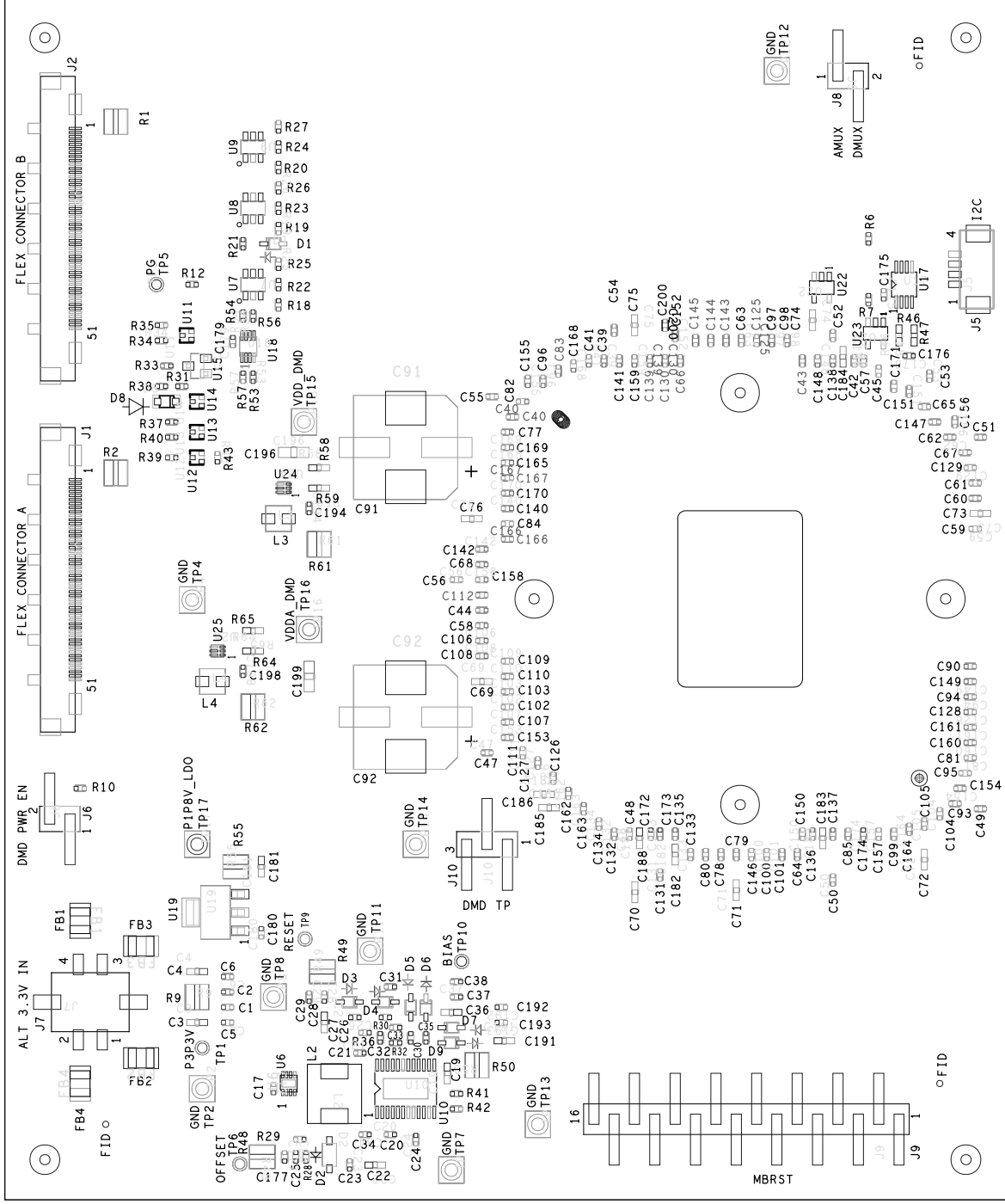
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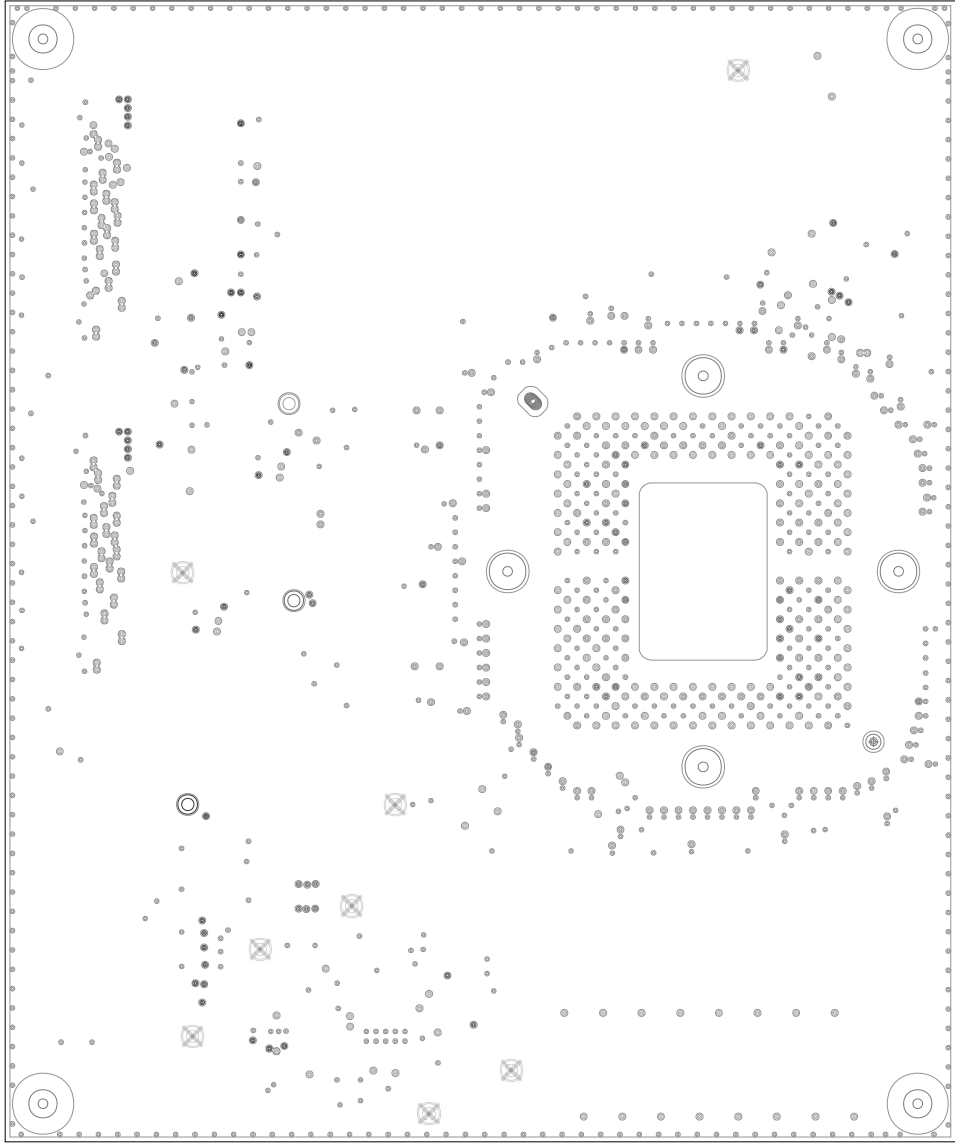
ART FILM - top



TEXAS INSTRUMENTS		ASSEMBLY - PRIMARY SIDE	
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	LAYER 1 - PRIMARY SIDE
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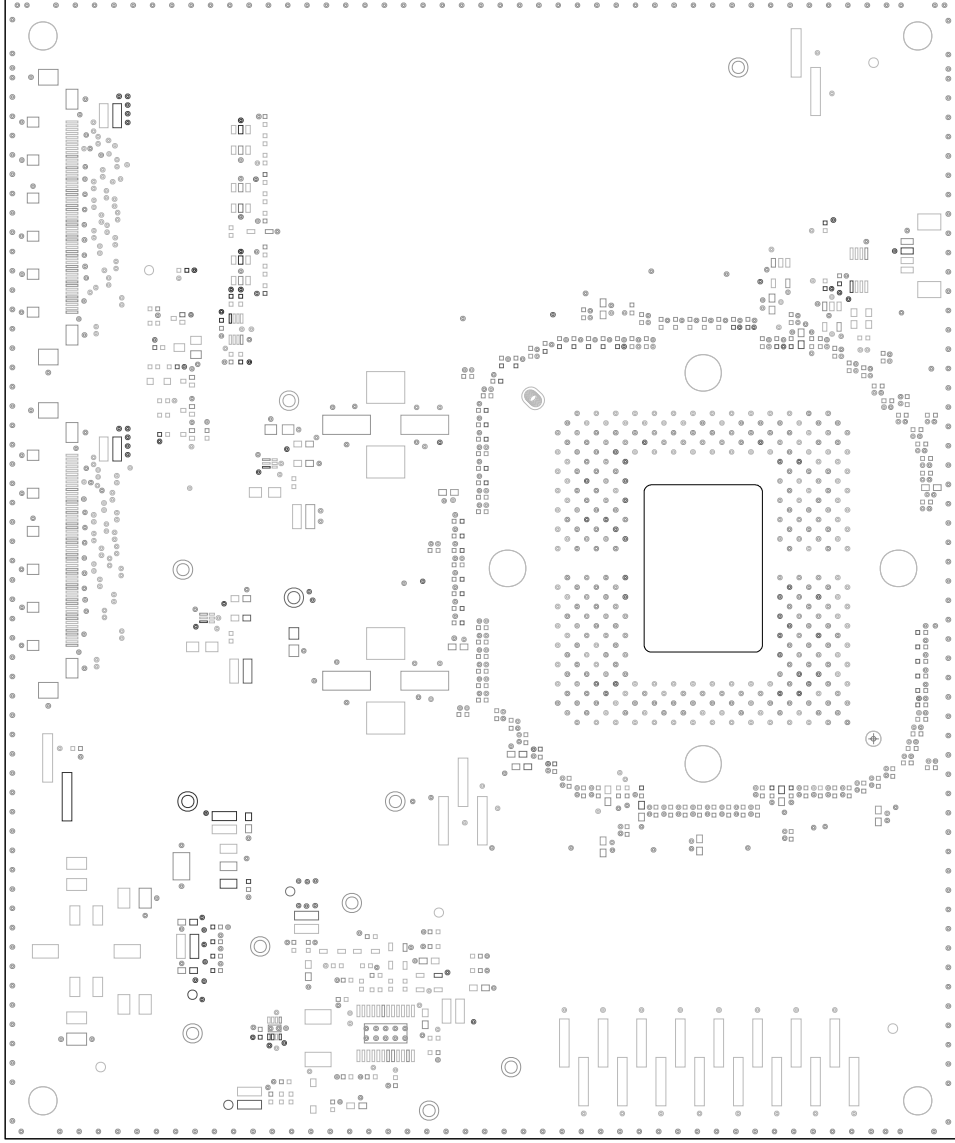


TEXAS INSTRUMENTS ASSEMBLY - PRIMARY SIDE	
BOARD NAME: 0.98 HSSI DMD BOARD	DESCRIPTION: SILKSCREEN - PRIMARY SIDE
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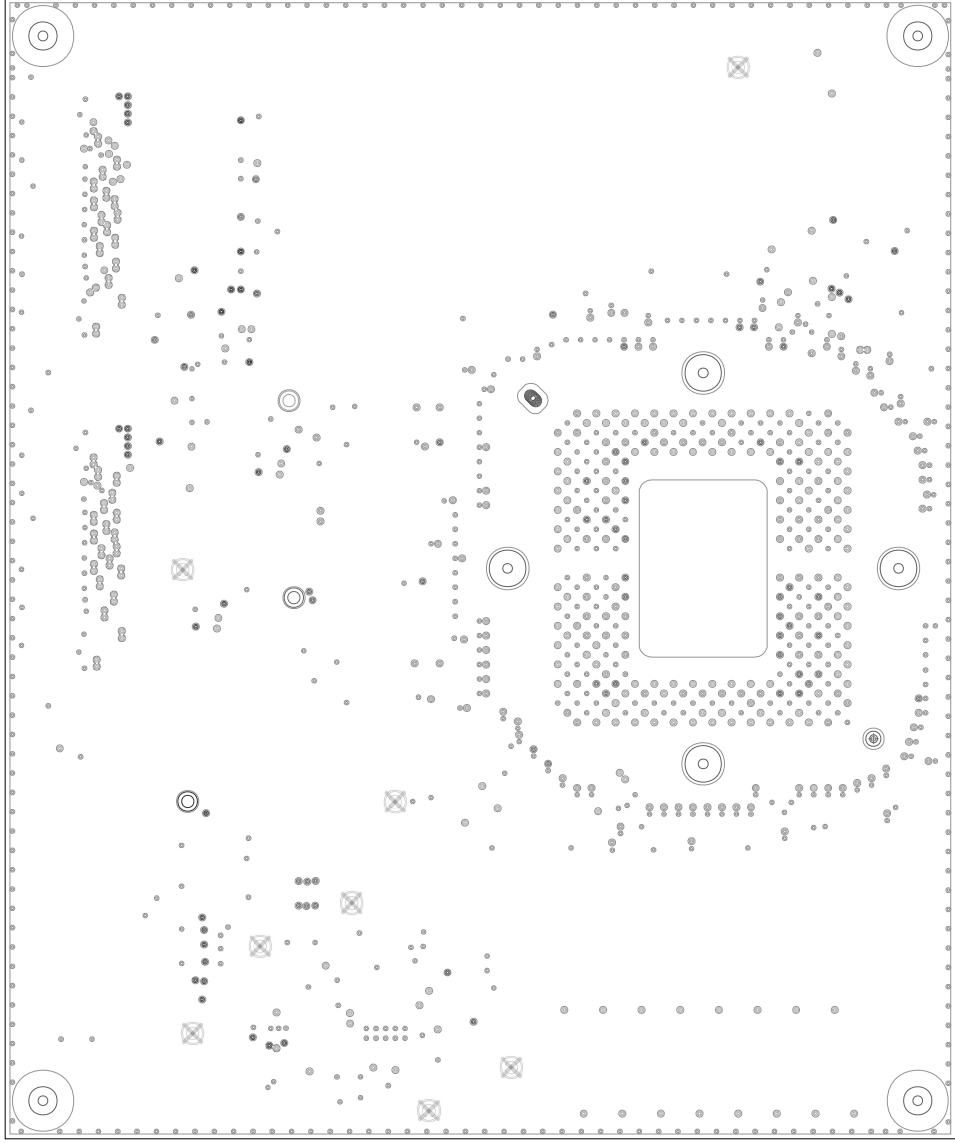
TEXAS INSTRUMENTS			
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	LAYER 7 - PWR PLANE
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ART FILM - smt



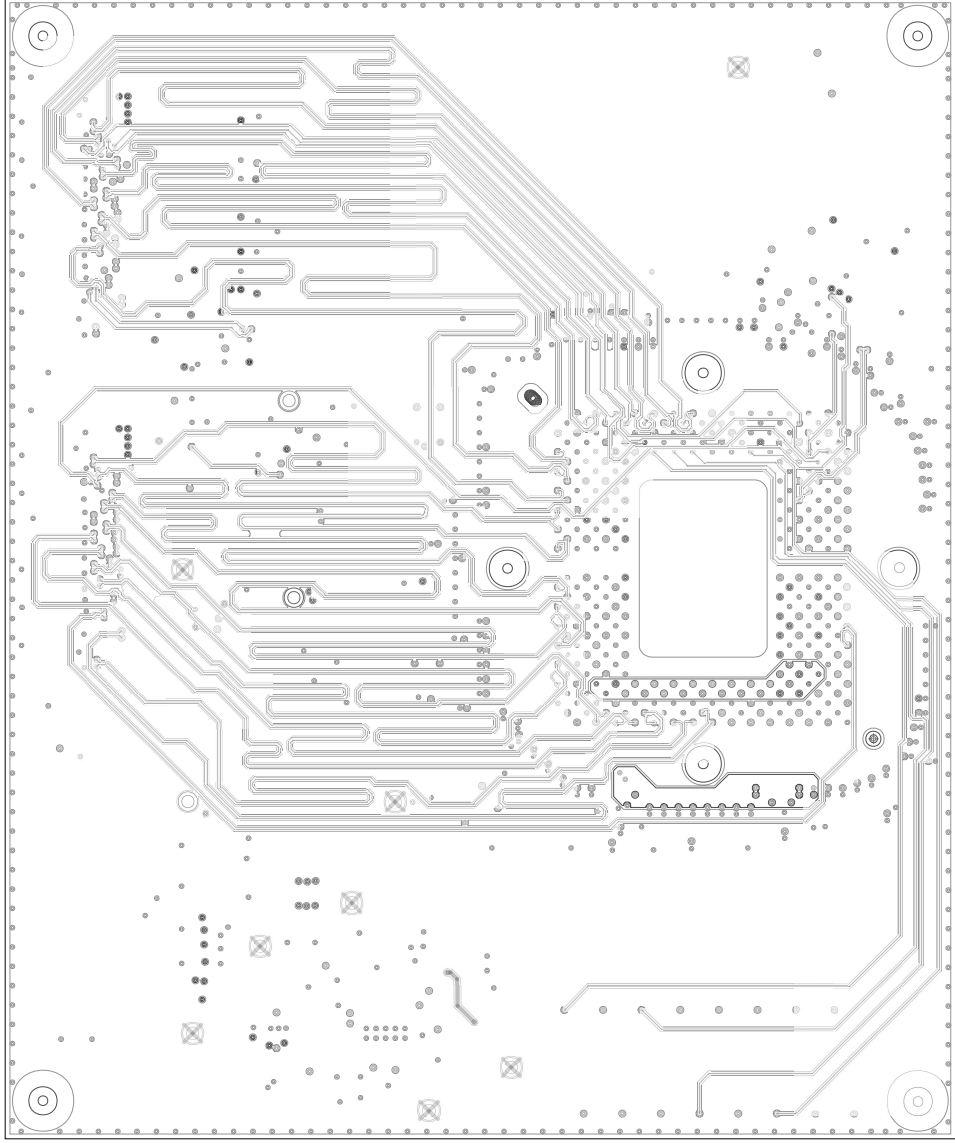
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ART FILM - smt



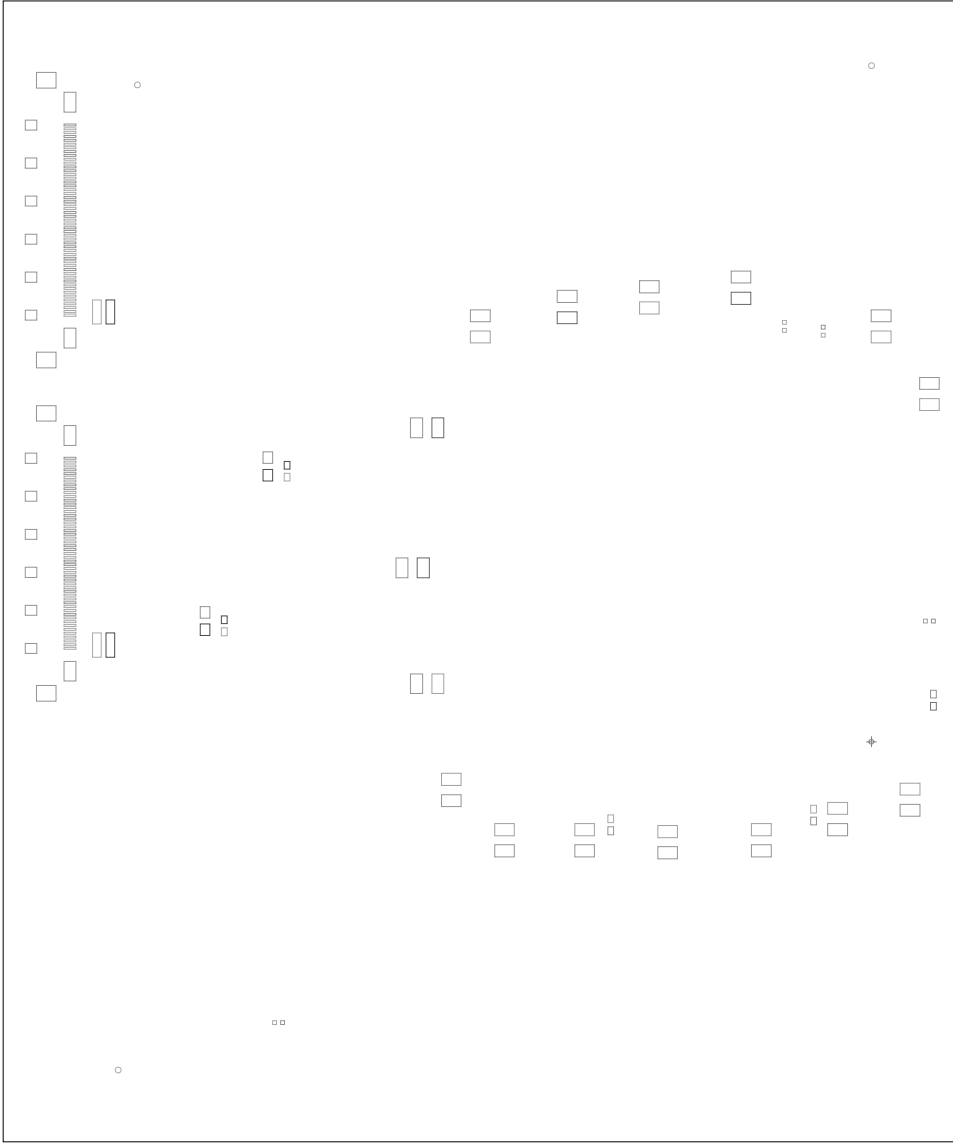
TEXAS INSTRUMENTS			
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	LAYER 5 - GND PLANE
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ART FILM - 146



TEXAS INSTRUMENTS			
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	LAYER 6 - SIGNAL
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ART FILM - 146



TEXAS INSTRUMENTS			
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